

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5080358

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DAIKI KOMATSU	08/01/2018
MAKOTO SHIBUYA	08/01/2018
YAN YI	08/02/2018
HAU NGUYEN	07/31/2018
LUU THANH NGUYEN	07/31/2018
ANINDYA PODDAR	08/01/2018
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Internal Address:	M/S 3999
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State/Country:	TEXAS
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16053199
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ATTORNEY DOCKET NUMBER:	TI-79067
NAME OF SUBMITTER:	ERIC HIGHMAN
SIGNATURE:	/Eric Highman/
DATE SIGNED:	08/02/2018

PATENT

Total Attachments: 4

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ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No(s) _____, filed _____;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

TITLE	PRINTED REPASSIVATION FOR WAFER CHIP SCALE PACKAGING		
NONPROVISIONAL APPLICATION NO.	16/053,199	FILING DATE	August 2, 2018
SIGNATURE OF INVENTOR	Daiki Komatsu		
PRINTED NAME OF INVENTOR	Daiki Komatsu		
DATE	8/1 2018		
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Application No. 16/053,199

Attorney Docket No. TI-79067


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Application No. 16/053,199

Attorney Docket No. TI-79067

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